

ON Semiconductor Sales Office ON Semiconductor Sales Office ON Semiconductor Sales Office uct/Process Change Notification of the change.	or < <u>Yasuhiro.lgarashi@onsemi.com</u> >. on (FPCN) sentto customers. FPCNs are issued 90 days prior			
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n of the change. <sup>•</sup> will consider this change acce				
This is a Final Product/Process Change Notification (FPCN) sentto customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>				
Date code				
nge 🔲 Assembly Change	Test Change Other			
terial Change duct specific change	<ul> <li>Datasheet/Product Doc change</li> <li>Shipping/Packaging/Marking</li> <li>Other:</li> </ul>			
r Sites:	External Foundry/Subcon Sites: None			
ce the addition of a new wafer f	fabrication site for the device covered in this notice.			
	fabrication site for the device covered i n this notice. tured at ON Semiconductor Co., Ltd, Niigata, Japan (OSNC)			
	tured at ON Semiconductor Co., Ltd, Niigata, Japan (OSNC)			



QV DEVICE NA RMS: PACKAGE:	ME: <u>1HP04CH-TL-W</u> <u>41658</u> <u>CPH3</u>				
Test	Specification		Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V		1,008 hrs	0/231
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss		1,008 hrs	0/231
HTSL	JESD22-A103	Ta=150°C		1,008 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min		15,000 cyc	0/231
тс	JESD22-A104	Ta= -55°C to +150°C		1,000 cyc	0/231
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias		96 hrs	0/231
Autoclave	JESD22-A102	121°C, 100% RH, 15psig, unbiased		96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C			
RSH	JESD22- B106	Ta = 265C, 10 sec			0/90
t <b>rical Characteris</b> e is no change in th	t <b>ic Summary:</b> e electrical performance. Datas	sheetspecificatio	ons remain unchanged.		
of Affected Stand	dard Parts:				
	Part Number		Qualification Vehicle		
1HP04CH-TL-W		1HP04CH-TL-W			